

# SOT566-1

plastic, heatsink small outline package; 24 leads

8 February 2016

Package information

## 1. Package summary

|                                |                                       |
|--------------------------------|---------------------------------------|
| Terminal position code         | D (double)                            |
| Package type descriptive code  | HSOP24                                |
| Package type industry code     | HSOP24                                |
| Package style descriptive code | HSOP (heatsink small outline package) |
| Package style suffix code      | NA (not applicable)                   |
| Package body material type     | P (plastic)                           |
| Mounting method type           | S (surface mount)                     |
| Issue date                     | 23-7-2003                             |

Table 1. Package summary

| Symbol         | Parameter                      |  | Min   | Typ | Nom  | Max  | Unit |
|----------------|--------------------------------|--|-------|-----|------|------|------|
| D              | package length                 |  | 15.8  | -   | 15.9 | 16   | mm   |
| E              | package width                  |  | 10.9  | -   | 11   | 11.1 | mm   |
| A              | seated height                  |  | [tbd] | -   | 3.7  | 3.7  | mm   |
| A <sub>2</sub> | package height                 |  | 3.2   | -   | 3.35 | 3.5  | mm   |
| n <sub>2</sub> | actual quantity of termination |  | -     | -   | 24   | -    |      |



2. Package outline

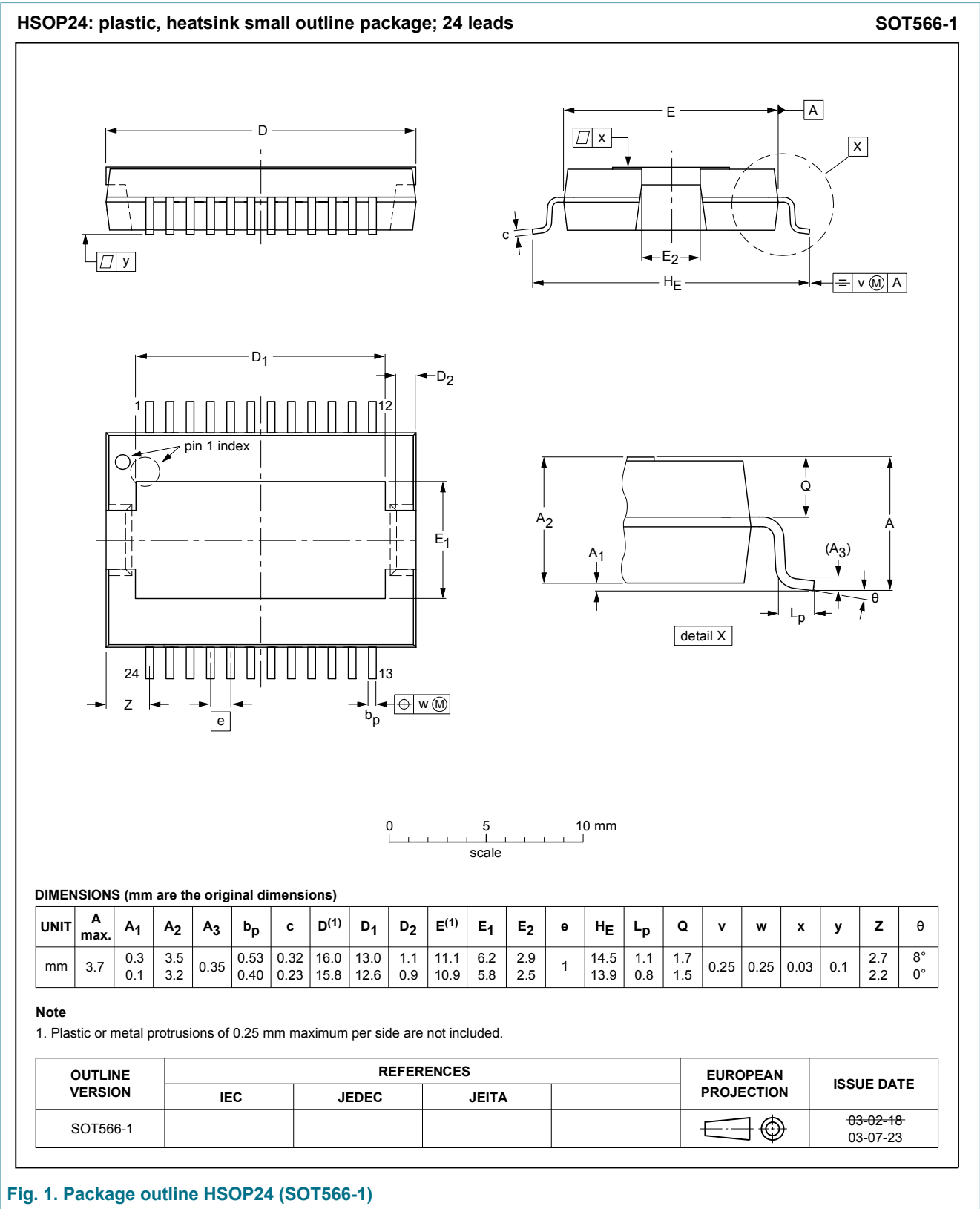


Fig. 1. Package outline HSOP24 (SOT566-1)

### 3. Legal information

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